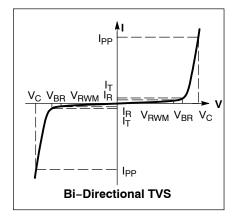
ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

١ ٨	,					
Symbol	Parameter					
I _{PP}	Maximum Reverse Peak Pulse Current					
V _C	Clamping Voltage @ I _{PP}					
V _{RWM}	Working Peak Reverse Voltage					
I _R	Maximum Reverse Leakage Current @ V _{RWM}					
V _{BR}	Breakdown Voltage @ I _T					
I _T	Test Current					
ΘV _{BR}	Maximum Temperature Coefficient of V _{BR}					



ELECTRICAL CHARACTERISTICS (Devices listed in bold, italic are ON Semiconductor Preferred devices.)

		V _{RWM}	I _R @	Breakdown Voltage			е	V _C @ I _{PP} (Note 6)			C _{typ}
	Device	(Note 4)	V _{RWM}	V _{BR} Volts (Note 5)			@ I _T	V _C	I _{PP}	ΘV _{BR}	(Note 7)
Device*	Marking	Volts	μΑ	Min	Nom	Max	mA	Volts	Amps	%/°C	pF
P6SMB11CAT3, G P6SMB12CAT3, G P6SMB13CAT3, G	11C 12C 13C	9.4 10.2 11.1	5 5 5	10.5 11.4 12.4	11.05 12 13.05	11.6 12.6 13.7	1 1 1	15.6 16.7 18.2	38 36 33	0.075 0.078 0.081	865 800 740
P6SMB15CAT3, G P6SMB16CAT3, G P6SMB18CAT3, G P6SMB20CAT3, G	15C 16C 18C 20C	12.8 13.6 15.3 17.1	5 5 5 5	14.3 15.2 17.1 19	15.05 16 18 20	15.8 16.8 18.9 21	1 1 1	21.2 22.5 25.2 27.7	28 27 24 22	0.084 0.086 0.088 0.09	645 610 545 490
P6SMB22CAT3, G P6SMB24CAT3, G P6SMB27CAT3, G P6SMB30CAT3, G	22C 24C 27C 30C	18.8 20.5 23.1 25.6	5 5 5 5	20.9 22.8 25.7 28.5	22 24 27.05 30	23.1 25.2 28.4 31.5	1 1 1	30.6 33.2 37.5 41.4	20 18 16 14.4	0.09 0.094 0.096 0.097	450 415 370 335
P6SMB33CAT3, G P6SMB36CAT3, G P6SMB39CAT3, G P6SMB43CAT3, G	33C 36C 39C 43C	28.2 30.8 33.3 36.8	5 5 5 5	31.4 34.2 37.1 40.9	33.05 36 39.05 43.05	34.7 37.8 41 45.2	1 1 1 1	45.7 49.9 53.9 59.3	13.2 12 11.2 10.1	0.098 0.099 0.1 0.101	305 280 260 240
P6SMB47CAT3, G P6SMB51CAT3, G P6SMB56CAT3, G P6SMB62CAT3, G	47C 51C 56C 62C	40.2 43.6 47.8 53	5 5 5 5	44.7 48.5 53.2 58.9	47.05 51.05 56 62	49.4 53.6 58.8 65.1	1 1 1	64.8 70.1 77 85	9.3 8.6 7.8 7.1	0.101 0.102 0.103 0.104	220 205 185 170
P6SMB68CAT3, G P6SMB75CAT3, G P6SMB82CAT3, G P6SMB91CAT3, G	68C 75C 82C 91C	58.1 64.1 70.1 77.8	5 5 5 5	64.6 71.3 77.9 86.5	68 75.05 82 91	71.4 78.8 86.1 95.5	1 1 1 1	92 103 113 125	6.5 5.8 5.3 4.8	0.104 0.105 0.105 0.106	155 140 130 120

^{4.} A transient suppressor is normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal to or greater than the DC or continuous peak operating voltage level.

^{5.} V_{BR} measured at pulse test current I_T at an ambient temperature of 25°C.
6. Surge current waveform per Figure 2 and derate per Figure 3 of the General Data – 600 Watt at the beginning of this group.

^{7.} Bias Voltage = 0 V, F = 1 MHz, T_J = 25°C

^{*}The "G" suffix indicates Pb-Free package available. Please refer back to Ordering Information on front page.

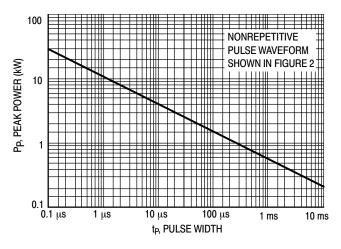


Figure 1. Pulse Rating Curve

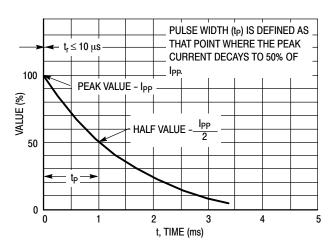


Figure 2. Pulse Waveform

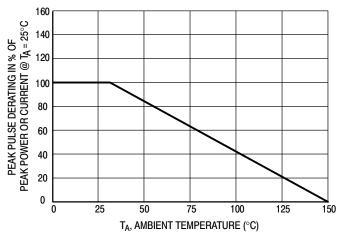


Figure 3. Pulse Derating Curve

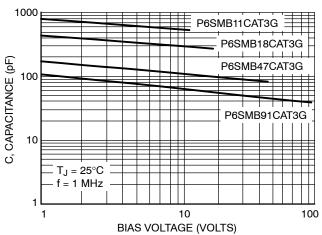
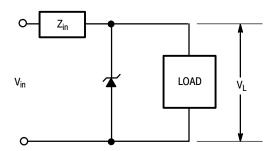


Figure 4. Typical Junction Capacitance vs. Bias Voltage

TYPICAL PROTECTION CIRCUIT



APPLICATION NOTES

RESPONSE TIME

In most applications, the transient suppressor device is placed in parallel with the equipment or component to be protected. In this situation, there is a time delay associated with the capacitance of the device and an overshoot condition associated with the inductance of the device and the inductance of the connection method. The capacitive effect is of minor importance in the parallel protection scheme because it only produces a time delay in the transition from the operating voltage to the clamp voltage as shown in Figure 4.

The inductive effects in the device are due to actual turn-on time (time required for the device to go from zero current to full current) and lead inductance. This inductive effect produces an overshoot in the voltage across the equipment or component being protected as shown in Figure 5. Minimizing this overshoot is very important in the application, since the main purpose for adding a transient suppressor is to clamp voltage spikes. The SMB series have a very good response time, typically < 1 ns and negligible inductance. However, external inductive effects could produce unacceptable overshoot. Proper circuit layout, minimum lead lengths and placing the

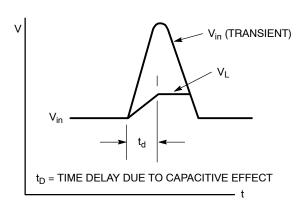
suppressor device as close as possible to the equipment or components to be protected will minimize this overshoot.

Some input impedance represented by Z_{in} is essential to prevent overstress of the protection device. This impedance should be as high as possible, without restricting the circuit operation.

DUTY CYCLE DERATING

The data of Figure 1 applies for non-repetitive conditions and at a lead temperature of 25°C. If the duty cycle increases, the peak power must be reduced as indicated by the curves of Figure 6. Average power must be derated as the lead or ambient temperature rises above 25°C. The average power derating curve normally given on data sheets may be normalized and used for this purpose.

At first glance the derating curves of Figure 6 appear to be in error as the 10 ms pulse has a higher derating factor than the 10 µs pulse. However, when the derating factor for a given pulse of Figure 6 is multiplied by the peak power value of Figure 1 for the same pulse, the results follow the expected trend.



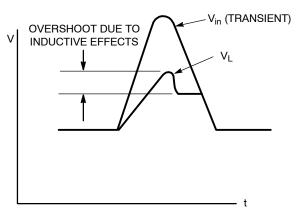


Figure 5.

Figure 6.

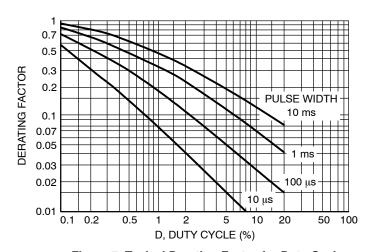


Figure 7. Typical Derating Factor for Duty Cycle

UL RECOGNITION

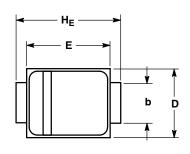
The entire series has *Underwriters Laboratory Recognition* for the classification of protectors (QVGQ2) under the UL standard for safety 497B and File #E210057. Many competitors only have one or two devices recognized or have recognition in a non-protective category. Some competitors have no recognition at all. With the UL497B recognition, our parts successfully passed several tests

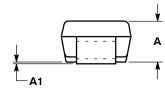
including Strike Voltage Breakdown test, Endurance Conditioning, Temperature test, Dielectric Voltage-Withstand test, Discharge test and several more.

Whereas, some competitors have only passed a flammability test for the package material, we have been recognized for much more to be included in their Protector category.

PACKAGE DIMENSIONS

SMB DO-214AA CASE 403A-03 ISSUE F



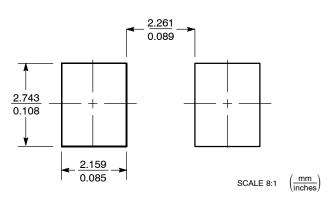


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	М	ILLIMETE	RS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.90	2.13	2.45	0.075	0.084	0.096	
A1	0.05	0.10	0.20	0.002	0.004	0.008	
b	1.96	2.03	2.20	0.077	0.080	0.087	
С	0.15	0.23	0.31	0.006	0.009	0.012	
D	3.30	3.56	3.95	0.130	0.140	0.156	
E	4.06	4.32	4.60	0.160	0.170	0.181	
HE	5.21	5.44	5.60	0.205	0.214	0.220	
L	0.76	1.02	1.60	0.030	0.040	0.063	
L1		0.51 REF		0.020 BEF			

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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